

**OBSOLETE – PART DISCONTINUED**

**Description**

The AZV358 is dual low-voltage (2.7V to 5.5V) operational amplifiers which have rail-to-rail output swing capability. The input common-mode voltage range includes ground. The chip exhibits excellent speed-power ratio, achieving 1MHz of bandwidth and 1V/μs of slew rate with low supply current.

The AZV358 is built with BiCMOS process. It has bipolar input and output stages for improved noise performance, low input offset voltage and higher output current drive.

The AZV358 is available in the packages of TSSOP-8 and MSOP-8. The small packages save space on PC boards and enable the design of small portable electronic devices. It also allows the designer to place the device closer to the signal source to reduce noise pickup and increase signal integrity.

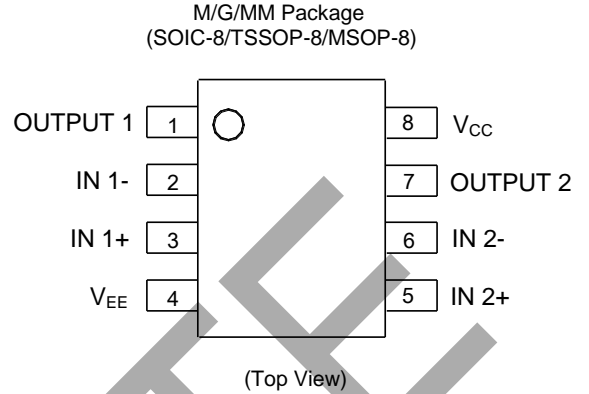
The AZV358 is also available in standard SOIC-8 package.

**Features**

(For  $V_{CC} = 5V$  and  $V_{EE} = 0V$ , typical unless otherwise noted)

- Guaranteed 2.7V to 5.5V Performance
- No Crossover Distortion
- Gain-Bandwidth Product 1MHz
- Industrial Temperature Range: -40°C to +85°C
- Low Supply Current: 210μA
- Rail-to-Rail Output Swing under 10kΩ Load:
  - $V_{OH}$  up to  $V_{CC} - 10mV$
  - $V_{OL}$  near to  $V_{EE} + 65mV$
- $V_{CM}$ : -0.1V to  $V_{CC} - 0.8V$
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](#) or your local Diodes representative.**  
<https://www.diodes.com/quality/product-definitions/>

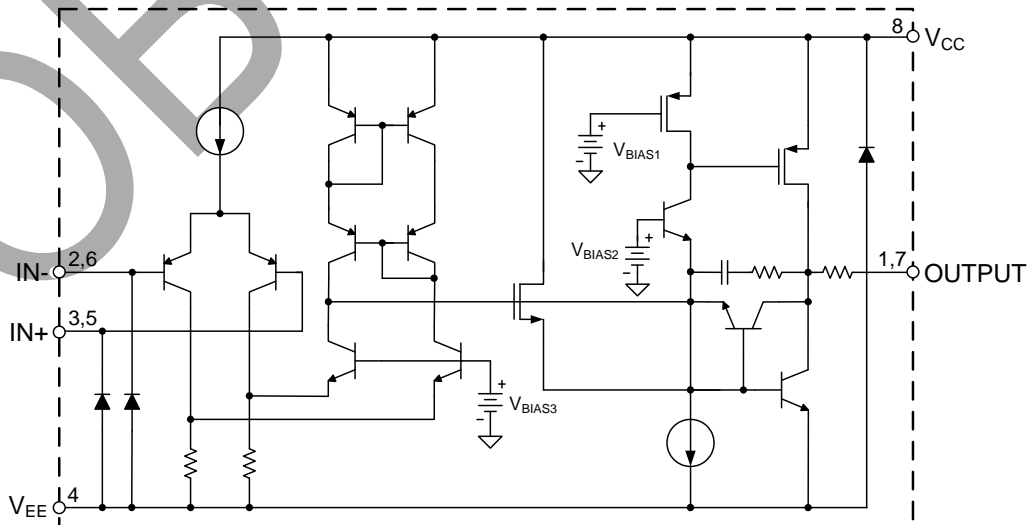
**Pin Assignments**



**Applications**

- Active filters
- Low-power, low-voltage applications
- General-purpose portable devices
- Cellular phones, cordless phones
- Battery-powered systems

**Functional Block Diagram**



**Absolute Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.) (Note 1)

Symbol	Parameter	Rating	Unit
$V_{CC}$	Power Supply Voltage	6	V
$T_J$	Operation Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-65 to +150	$^\circ\text{C}$
$T_{LEAD}$	Lead Temperature (Soldering, 10 seconds)	+260	$^\circ\text{C}$
—	ESD (Machine Model)	200	V
—	ESD (Human Body Model)	2000	V

Note: 1. Stresses greater than those listed under *Absolute Maximum Ratings* can cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to *Absolute Maximum Ratings* for extended periods can affect device reliability.

**Recommended Operating Conditions**

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	Supply Voltage	2.7	5.5	V
$T_A$	Ambient Operating Temperature Range	-40	+85	$^\circ\text{C}$

**2.7V Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , **bold** typeface applies over  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ,  $V_{CC} = 2.7\text{V}$ ,  $V_{EE} = 0\text{V}$ ,  $V_{CM} = 1.0\text{V}$ ,  $V_O = V_{CC}/2$  and  $R_L > 1\text{M}\Omega$ , unless otherwise specified.) (Note 2)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IO}$	Input Offset Voltage	—	—	1.7	7	mV
		—	—	—	<b>9</b>	
$I_B$	Input Bias Current	—	—	11	250	nA
		—	—	—	<b>500</b>	
$I_{IO}$	Input Offset Current	—	—	5	50	nA
		—	—	—	<b>150</b>	
$V_{CM}$	Input Common Mode Voltage Range	For $CMRR \geq 50\text{dB}$	-0.1	—	1.9	V
$I_{CC}$	Supply Current	$V_O = V_{CC}/2$ , $A_{vCL} = 1$ No load	—	140	340	$\mu\text{A}$
			—	—	<b>420</b>	
CMRR	Common Mode Rejection Ratio	$0 \leq V_{CM} \leq 1.7\text{V}$	50	63	—	dB
PSRR	Power Supply Rejection Ratio	$2.7\text{V} \leq V_{CC} \leq 5\text{V}$ $V_O = 1\text{V}$	50	60	—	dB
$I_{SOURCE}$	Output Short-Circuit Current	$V_O = 0\text{V}$	5	20	—	mA
$I_{SINK}$		$V_O = 2.7\text{V}$	10	30	—	mA
$V_{OH}$	Output Voltage Swing	$R_L = 10\text{k}\Omega$ to $1.35\text{V}$	2.60	2.69	—	V
$V_{OL}$			—	60	180	mV
GBWP	Gain Bandwidth Product	$C_L = 200\text{pF}$	—	1	—	MHz
$\phi_M$	Phase Margin	—	—	60	—	deg
$G_M$	Gain Margin	—	—	10	—	dB

Note: 2. Limits over the full temperature are guaranteed by design, but not tested in production.

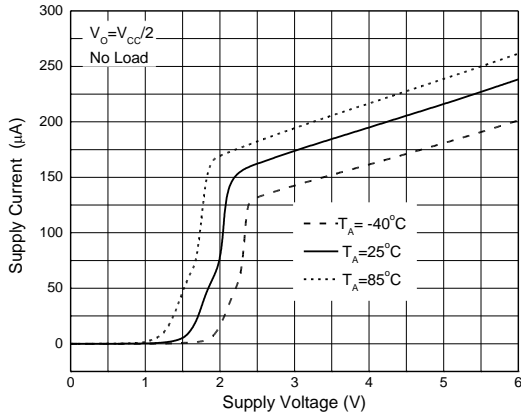
**5V Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , **bold** typeface applies over  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ,  $V_{CC} = 5\text{V}$ ,  $V_{EE} = 0\text{V}$ ,  $V_{CM} = 2.0\text{V}$ ,  $V_O = V_{CC}/2$  and  $R_L > 1\text{M}\Omega$ , unless otherwise specified.) (Note 2)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit		
$V_{IO}$	Input Offset Voltage	—	—	1.7	7	mV		
		—	—	—	<b>9</b>			
$I_B$	Input Bias Current	—	—	15	250	nA		
		—	—	—	<b>500</b>			
$I_{IO}$	Input Offset Current	—	—	5	50	nA		
		—	—	—	<b>150</b>			
$V_{CM}$	Input Common Mode Voltage Range	For $CMRR \geq 50\text{dB}$	-0.1	—	4.2	V		
$I_{CC}$	Supply Current	$V_O = V_{CC}/2$ , $A_{VCL} = 1$ No load	—	210	440	$\mu\text{A}$		
			—	—	<b>615</b>			
$G_V$	Large-Signal Voltage Gain	$R_L = 2\text{k}\Omega$	84	100	—	dB		
			<b>80</b>	—	—			
CMRR	Common Mode Rejection Ratio	$0 \leq V_{CM} \leq 4\text{V}$	50	63	—	dB		
PSRR	Power Supply Rejection Ratio	$2.7\text{V} \leq V_{CC} \leq 5\text{V}$ $V_O = 1\text{V}$ , $V_{CM} = 1\text{V}$	50	60	—	dB		
$I_{SOURCE}$	Output Short-Circuit Current	$V_O = 0\text{V}$	5	60	—	mA		
$I_{SINK}$		$V_O = 5\text{V}$	10	160	—	mA		
$V_{OH}$	Output Voltage Swing	$R_L = 2\text{k}\Omega$ to 2.5V	4.7	4.96	—	V		
			<b>4.6</b>	—	—			
		$R_L = 10\text{k}\Omega$ to 2.5V	4.9	4.99	—			
<b>4.8</b>			—	—				
$V_{OL}$			$R_L = 2\text{k}\Omega$ to 2.5V	—	120		300	mV
				—	—		<b>400</b>	
	$R_L = 10\text{k}\Omega$ to 2.5V		—	65	180			
			—	—	<b>280</b>			
SR	Slew Rate	—	1	—	V/ $\mu\text{s}$			
GBWP	Gain Bandwidth Product	$C_L = 200\text{pF}$	—	1	—	MHz		
$\phi_M$	Phase Margin	—	—	60	—	deg		
GM	Gain Margin	—	—	10	—	dB		

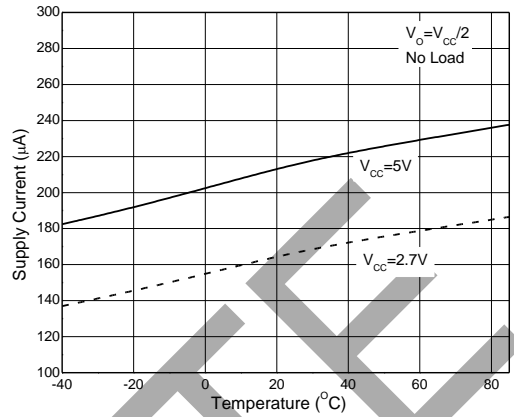
Note: 2. Limits over the full temperature are guaranteed by design, but not tested in production.

**Performance Characteristics**

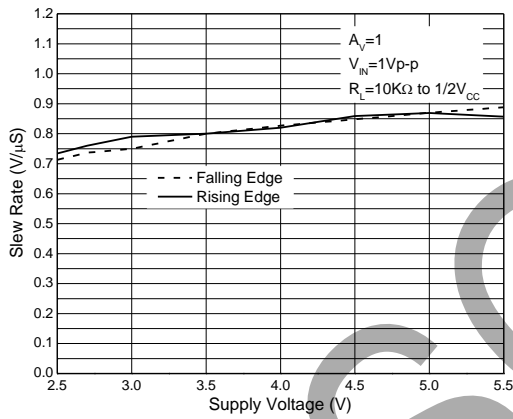
**Supply Current vs. Supply Voltage**



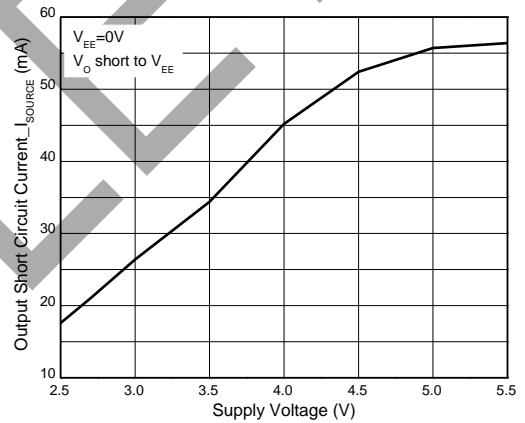
**Supply Current vs. Temperature**



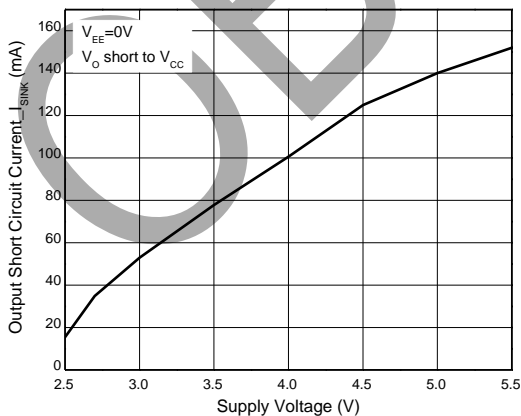
**Slew Rate vs. Supply Voltage**



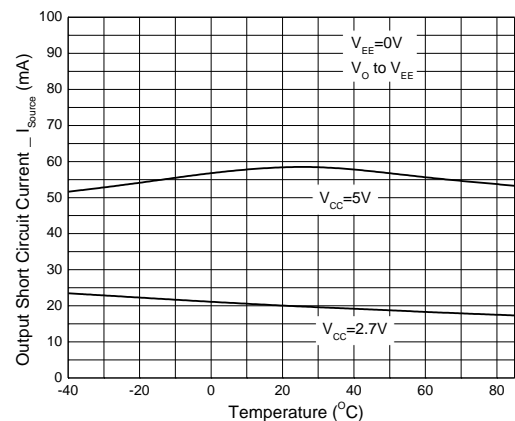
**Output Short-Circuit Current vs. Supply Voltage**



**Output Short-Circuit Current vs. Supply Voltage**



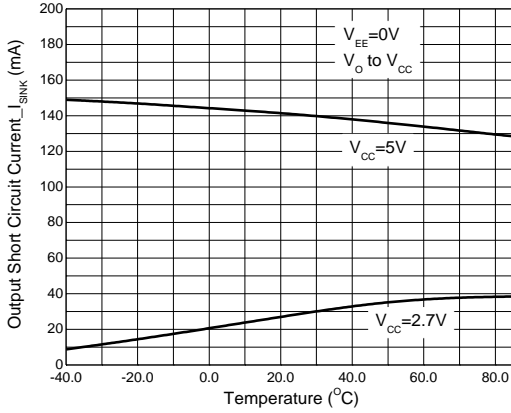
**Output Short-Circuit Current vs. Temperature**



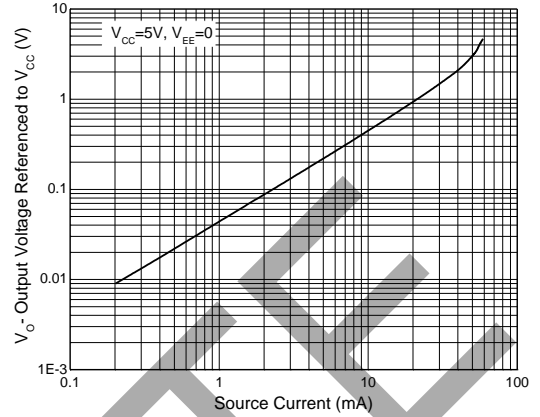
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**Performance Characteristics** (continued)

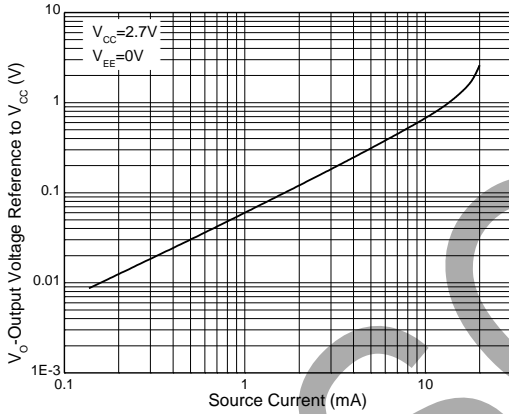
**Output Short-Circuit Current vs. Temperature**



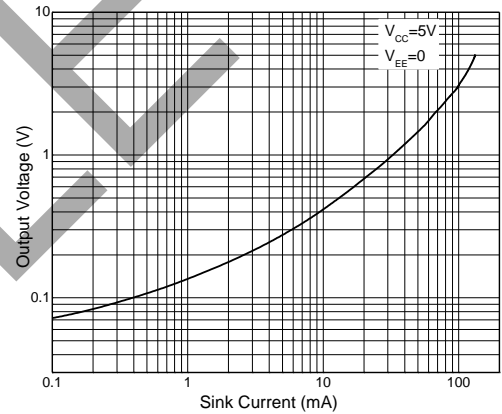
**Output Voltage vs. Output Source Current**



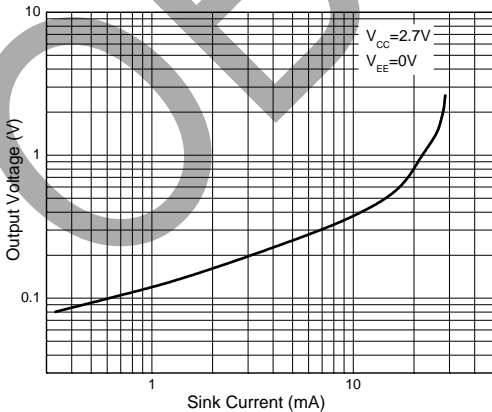
**Output Voltage vs. Output Source Current**



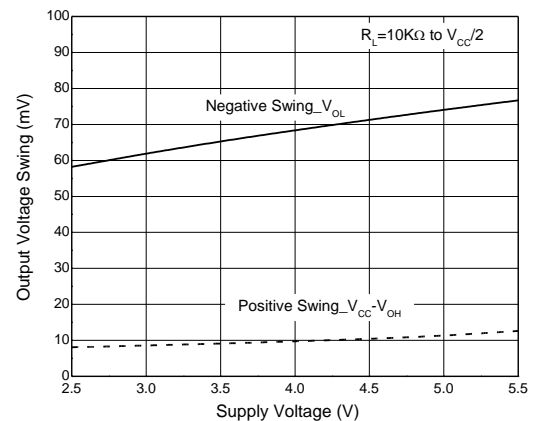
**Output Voltage vs. Output Sink Current**



**Output Voltage vs. Output Sink Current**



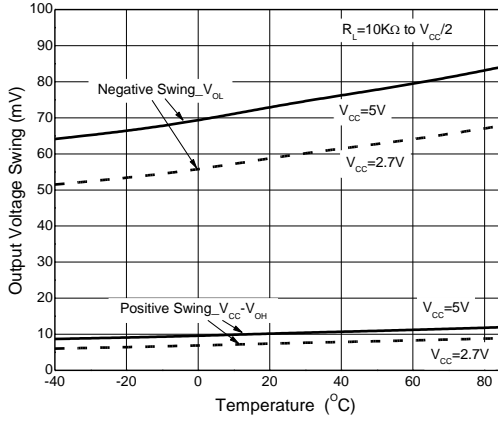
**Output Voltage Swing vs. Supply Voltage**



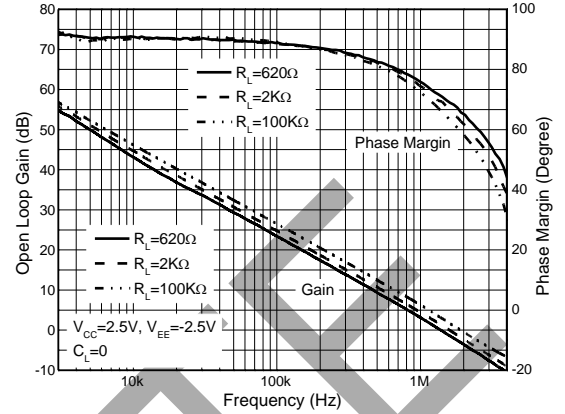
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**Performance Characteristics** (continued)

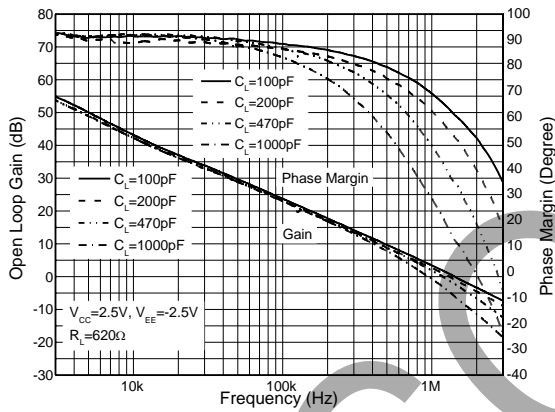
**Output Voltage Swing vs. Temperature**



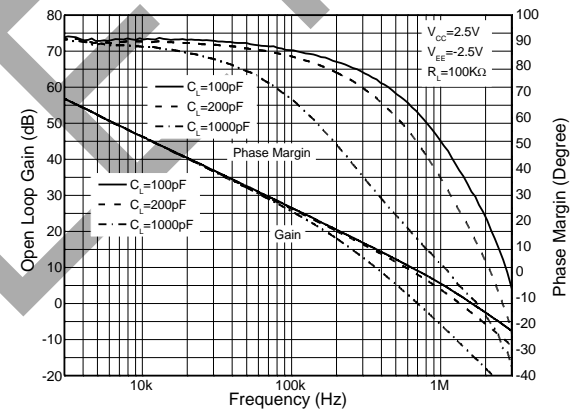
**Gain and Phase vs. Frequency and Resistive Load**



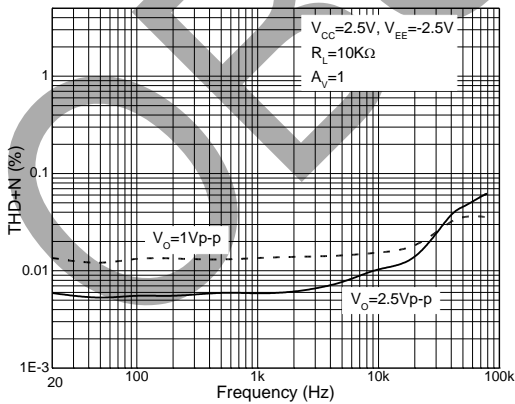
**Gain and Phase vs. Frequency and Capacitive Load**



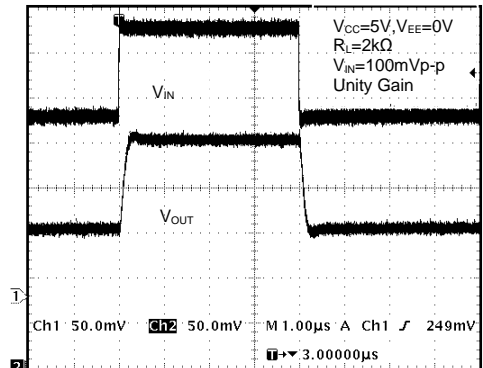
**Gain and Phase vs. Frequency and Capacitive Load**



**THD+N vs. Frequency**

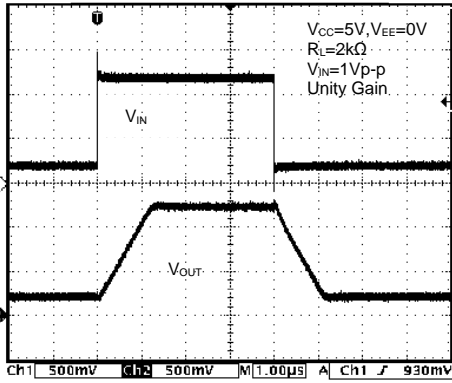


**Non-Inverting Input Small-Signal Pulse Response**

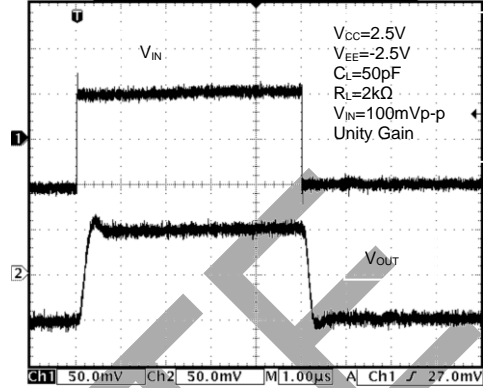


**Performance Characteristics** (continued)

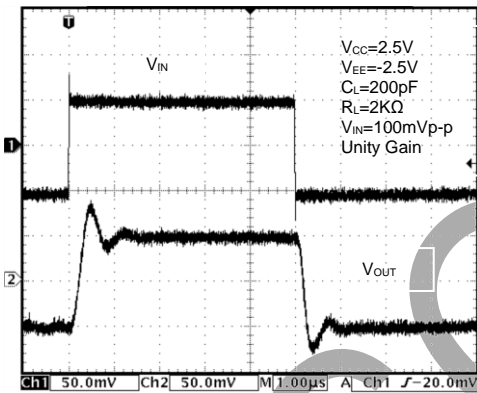
**Non-Inverting Input Large Signal Pulse Response**



**Non-Inverting Input Small-Signal Response**



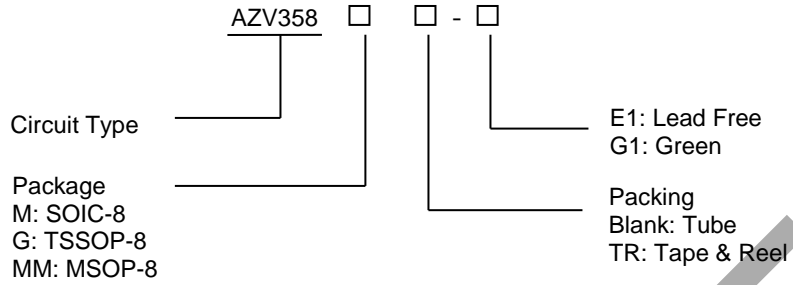
**Non-Inverting Input Small-Signal Response**



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**Ordering Information**



Package	Temperature Range	Orderable Part Number		Marking ID		Packing
		Lead Free	Green	Lead Free	Green	
SOIC-8	-40 to +85°C	AZV358M-E1	AZV358M-G1	AZV358M-E1	AZV358M-G1	Tube
		AZV358MTR-E1	AZV358MTR-G1	AZV358M-E1	AZV358M-G1	Tape & Reel
TSSOP-8	-40 to +85°C	AZV358G-E1	AZV358G-G1	EG3E	GG3E	Tube
		AZV358GTR-E1	AZV358GTR-G1	EG3E	GG3E	Tape & Reel
MSOP-8	-40 to +85°C	AZV358MM-E1	AZV358MM-G1	AZV358MM-E1	AZV358MM-G1	Tube
		AZV358MMTR-E1	AZV358MMTR-G1	AZV358MM-E1	AZV358MM-G1	Tape & Reel

Note: 3. Diodes Incorporated's Pb-free products, as designated with "E1" suffix in the part number, are RoHS compliant. Products with "G1" suffix are available in green packages.

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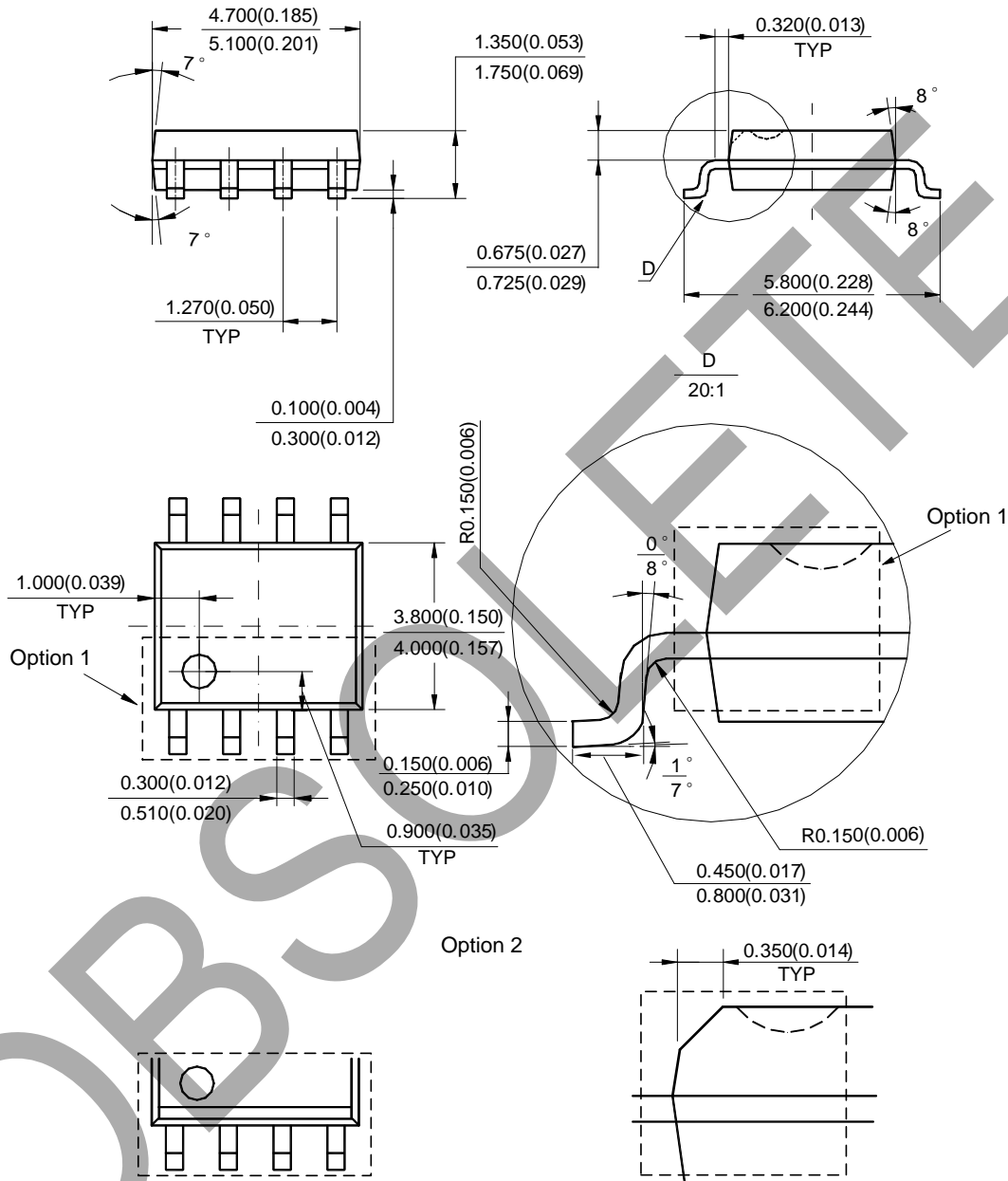
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**Package Outline Dimensions** (All dimensions in mm(inch).)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOIC-8**



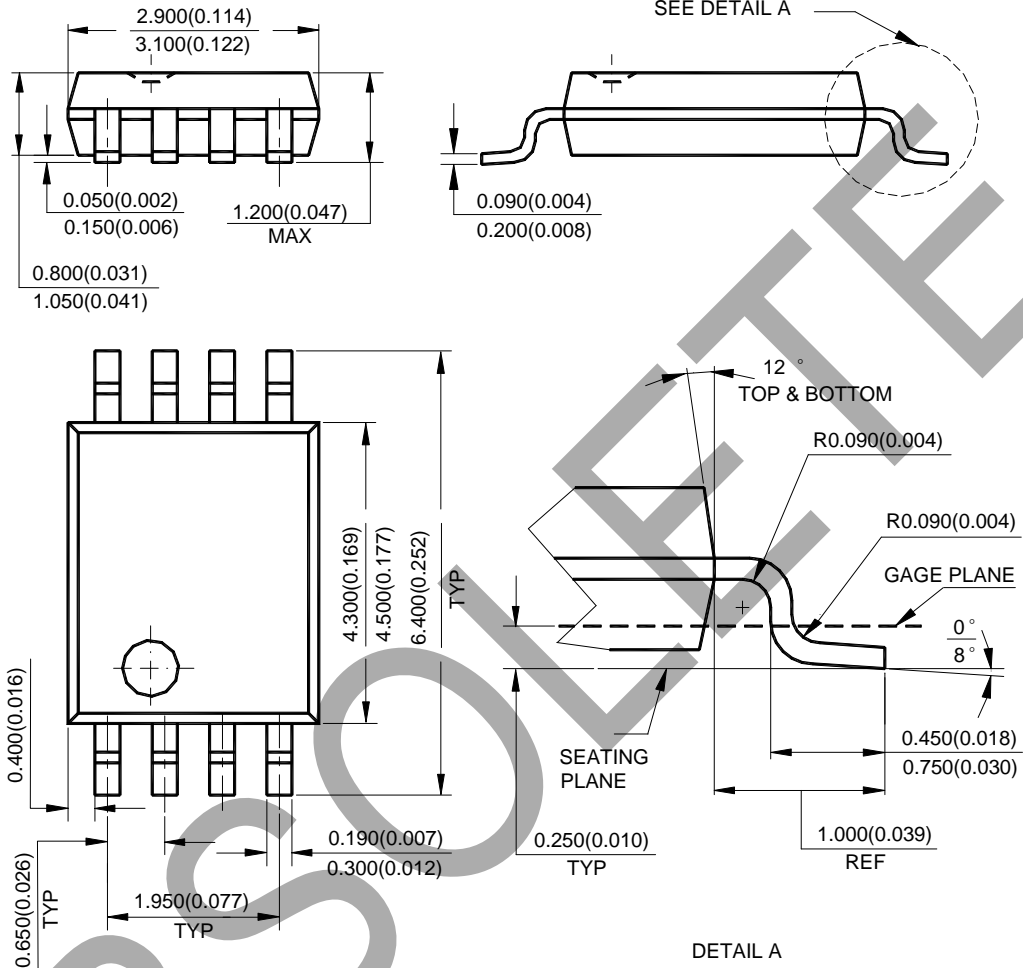
Note: Eject hole, oriented hole and mold mark is optional.

OBSOLETE - PART DISCONTINUED

**Package Outline Dimensions** (continued) (All dimensions in mm(inch).)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**TSSOP-8**



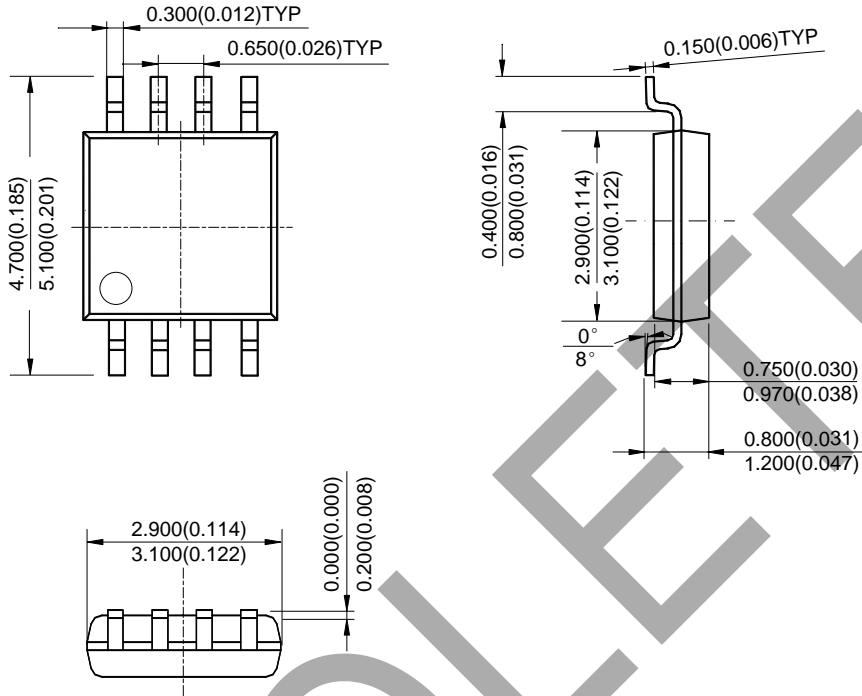
Note: Eject hole, oriented hole and mold mark is optional.

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**Package Outline Dimensions** (continued) (All dimensions in mm(inch).)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**MSOP-8**



Note: Eject hole, oriented hole and mold mark is optional.

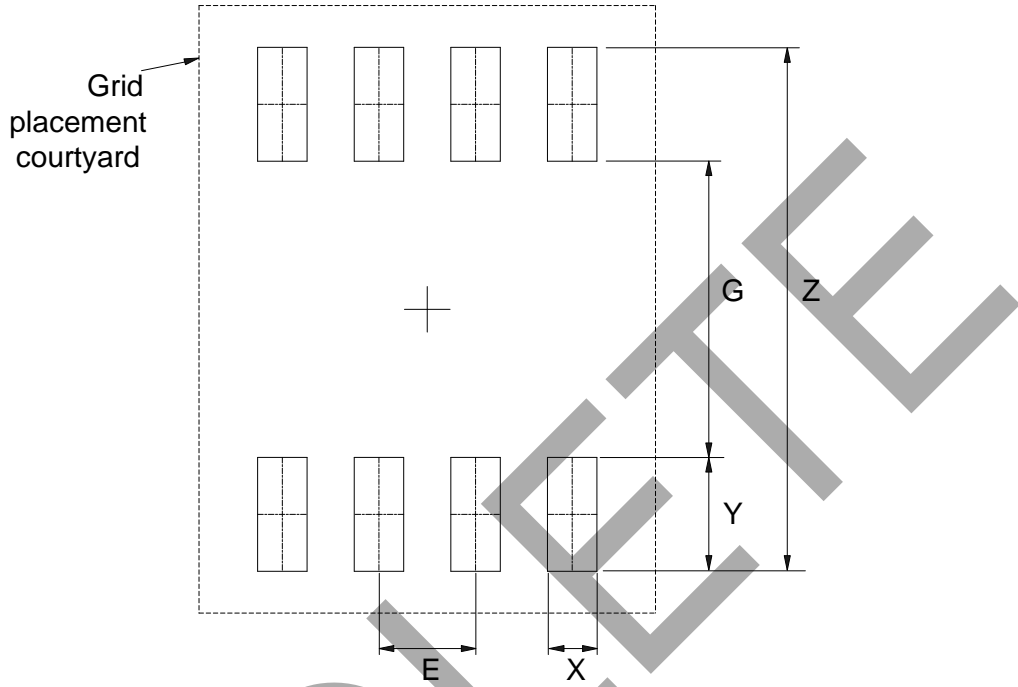
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**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOIC-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)
Value	6.900/0.272	3.900/0.154	0.650/0.026	1.500/0.059	1.270/0.050

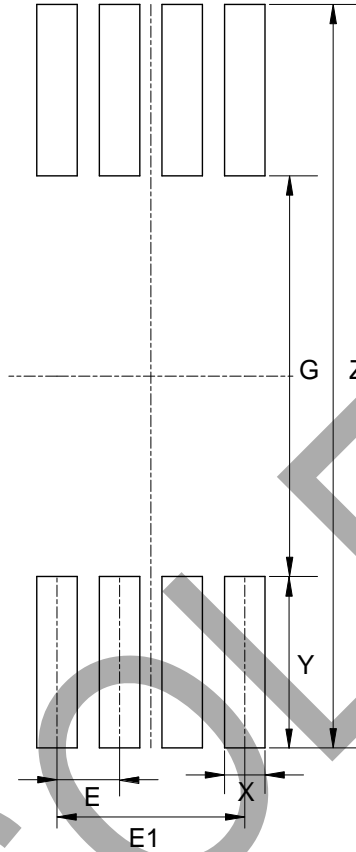
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**Suggested Pad Layout** (continued)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

TSSOP-8



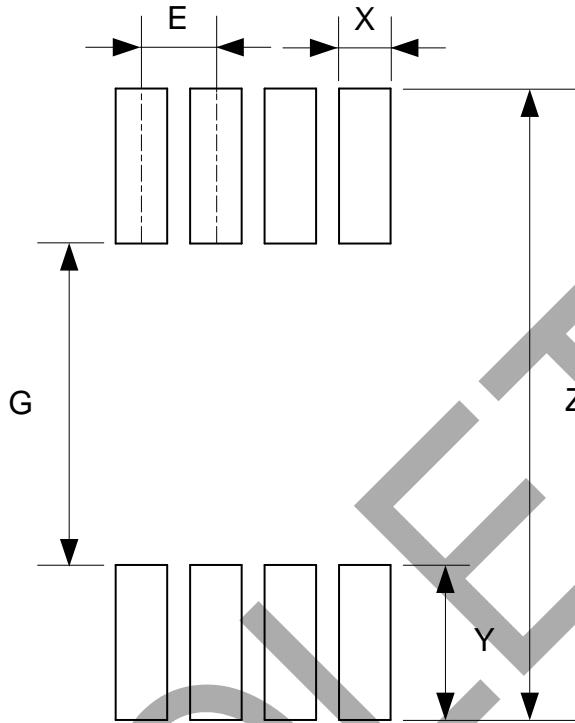
Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)	E1 (mm)/(inch)
Value	7.720/0.304	4.160/0.164	0.420/0.017	1.780/0.070	0.650/0.026	1.950/0.077

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**Suggested Pad Layout** (continued)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

MSOP-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)
Value	5.500/0.217	2.800/0.110	0.450/0.018	1.350/0.053	0.650/0.026

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